

DO NOT SCALE DRAWING

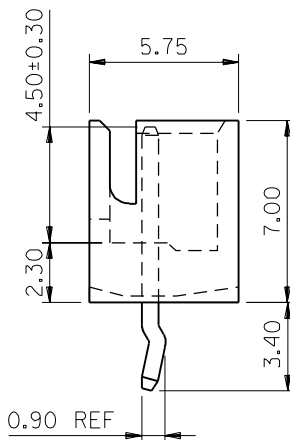
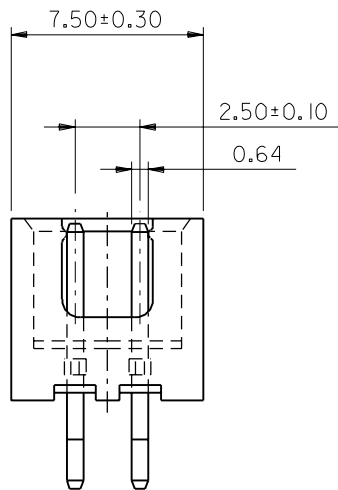
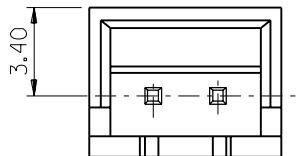
CADFILE NO. S6728001.S01

SIMILAR ITEM

EDP NO.

ENG. NO SD-67280-***0

GC.DGN REV A
96/06/12 LEVEL 3



NOTES

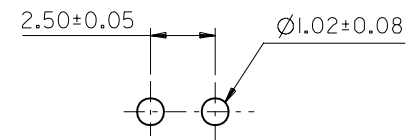
1.MATERIAL:

WAFER: POLYESTER,UL 94V-0

COLOR: NATURAL

POST: BRASS,TIN PLATED,THICKNESS=200 MICROINCH MINMUM.

2.PRODUCT SPEC.: PS-67261-003



PC BOARD HOLE LAYOUT
RECOMMENDED PCB THICKNESS 1.60mm

ADD NOTES		CHANGE MATERIAL		UPDATE TITLE DESCRIPTION		R.T.M.		NEW RELEASE		DESCRIPTION	REV
EC NO. T2002-0156 DRWN: LZHAO 2002/01/03 CHK: LUJING 2002/01/07 APPR: SAMHUANG 2002/01/07		EC NO. T2001-0109 DRWN: TITON Huang 02/20/01 CHK: Vincent Lin APPR: Mega Lin		EC NO. T2001-0009 DRWN: GRACE LEU 00/08/28 CHK: EMILY HSU APPR: MEGA LIN		EC NO. T2000-0193 DRWN: G.Wang 00/03/13 CHK: WILSON CHANG APPR: MEGA LIN		EC NO. T2000-0043 DRWN: EMILY HSU 99/07/17 CHK: WILSON CHANG APPR: MEGA LIN			
D1		D		C		B		A			
				</							

DIMENSIONS:		SHT	REV
☐ mm	☐ INCH		
☐ mm	☐ INCH		
☒ mm ONLY			

REVISION ON CAD ONLY

DESIGN UNITS
☒ mm ☐ INCH

THIRD ANGLE PROJECTION

DRAWN BY & DATE
EMILY HSU 99/07/17

CHECKED BY & DATE
WILSON CHANG 99/07/17

APPROVED BY & DATE
MEGA LIN 99/07/17

CAD FILENAME
S6728001.S01

TITLE:
2.50 MM PITCH
WIRE TO BOARD, HEADER ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO.
SEE CHART

DRAWING NO.
SD-67280-001

SHEET NO.
1 OF 2

SIZE
A3

